

28. (Amended) An apparatus for making electrical contact with a plurality of bond pads on an integrated circuit device comprising: a first fan out substrate having a first surface; said first surface having a plurality of contact locations; a plurality of ball bonds attached to said plurality of contact locations; a plurality of compliant wires extending outward from said ball bonds, away from said first surface fan out substrate; a plurality of ball shaped contacts on the ends of said plurality of wires; and a means for maintaining said plurality of balls in substantially fixed positions.

48. (Added) A structure according to claim 1 wherein said compliant elongated electrical conductor is shaped to compliantly respond when the said compliant elongated electrical conductors are pressed against and withdraw from a surface against which said second ends are pressed.

49. (Added) A structure according to claim 1 wherein said means for maintaining comprises a sheet of material comprising openings comprising a large region and a small region.

50. (Added) A method according to claim 1 wherein said compliant elongated electrical conductor is shaped to compliantly respond when the said compliant elongated electrical conductors are pressed against and withdraw from a surface against which said second ends are pressed.

51. (Added) A method according to claim 41 wherein said means for maintaining comprises openings comprising a large region and a small region, said compliant elongated electrical conductors are first inserted through said large region and then moved to said small region.

52. (Added) A structure comprising:

a substrate having a surface;

a plurality of elongated electrical conductors extending away from said surface;

each of said elongated electrical conductors having a first end affixed to said surface and a second end projecting away from said surface;

said second end is at a non-orthogonal angle with respect to said surface;

there being a plurality of said second ends; and

a means for positioning and maintaining said plurality of said second ends in substantially fixed positions.

53. (Added) A structure according to claim 52 wherein said non-orthogonal angle is from between 5 degrees and 60 degrees.

54. (Added) A structure according to claim 52 wherein said elongated electrical conductor comprises a bend.

55. (Added) An apparatus for making electrical contact with a plurality of bond pads on an integrated circuit device comprising: a first fan out substrate having a first surface; said first surface having a plurality of contact locations; a plurality of ball bonds attached to said plurality of contact locations; a plurality of wires extending outward from said ball bonds, away from said first surface fan out substrate; a plurality of ball shaped contacts on the ends of said plurality of wires; and a means for maintaining said plurality of balls in substantially fixed positions; said wire has a first end and electrically